## High Efficiency, 16.0V, 10.0A Synchronous Boost(Step-Up) Regulator

Preliminary Specification

### **General Description**

FH47120 develops a high efficiency, high power density synchronous boost regulator. The device adopts adaptive constant off time and current mode control. The integrated low RDS(ON) switches minimize the conduction loss.

FH47120 provides selectable PFM/PWM light load operation mode. The device features cycle by cycle peak current limit. Low output voltage ripple and small external inductor and capacitor size are achieved with programmable pseudo-constant frequency.

### **Applications**

- Power Bank
- High Power AP
- E-Cigarette
- Bluetooth Speaker

### **Features**

- Input Range: 2.8 to 16.0V
- Programmable Pseudo-constant Frequency: 300kHz-2MHz
- Low  $R_{DS(ON)}$  for Internal Switch Main FET:  $10m\Omega$ Rectifier FET:  $20m\Omega$
- PFM/PWM Selectable Light Load Operation Mode
- Internal Loop Compensation
- Programmable Peak Current Limit
- Internal Soft-start Time Limit the Inrush Current
- Input Voltage UVLO
- Over Temperature Protection
- Over Voltage Protection
- RoHS Compliant and Halogen Free
- Compact Package: OFN3×3-20L

# **Typical Applications**

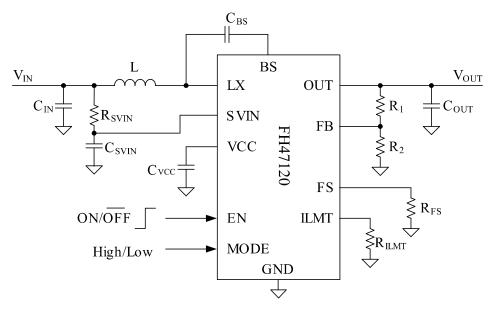
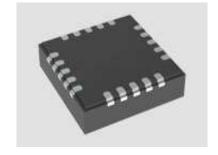
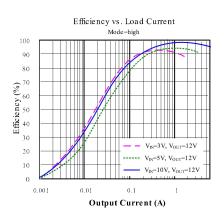


Figure 1. Schematic Diagram

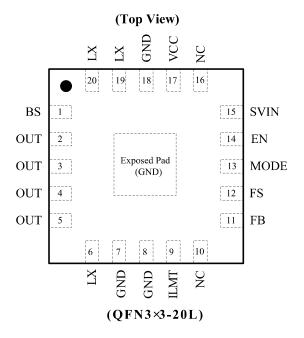






# **Pin Configuration**

Preliminary Specification



## **Pin Description**

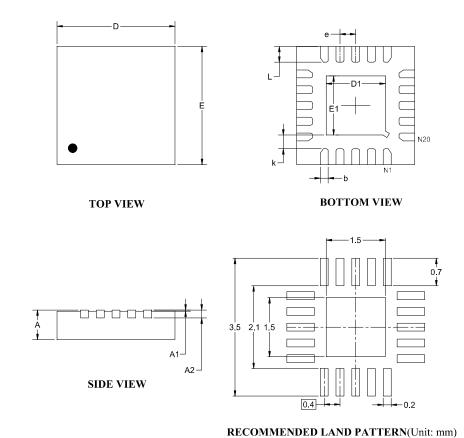
Pin Name	Pin Number	Pin Description			
BS	1	Boost-strap pin. Supply Rectifier FET's gate driver. Decouple this pin to the LX pin with a 0.1µF ceramic capacitor			
OUT	2,3,4,5	The Boost converter output pin.			
LX	6,19,20	Inductor node. Connect an inductor from power input to the LX pin.			
GND	7,8,18, EP	Ground pin of the IC.			
ILMT	9	Switch peak current limit setting. Connect a resistor from this pin to GND. $I_{LMT}(A){=}1200/R_{ILMT}(k\Omega){-}2$			
NC	10,16	Not connected.			
FB	11	Feedback pin. Connected to the center of resistor voltage divider to program the output voltage: $V_{OUT}=1$ $V\times(R_1/R_2+1)$			
FS	12	Switching frequency setting pin. Connect a resistor from this pin to ground to program the switching frequency. $f_S(kHz) = 73565/R_{FS}(k\Omega) + 300$			
MODE	13	Operating mode selection under light load. Pull this pin low for PFM operation, and pull this pin high or leave it floating for PWM operation.			
EN	14	Enable control. Pull high to turn on the IC. Do not leave it floating.			
SVIN	15	IC power supply input pin. Decouple this pin to the GND pin with a $1\mu F$ ceramic capacitor.			
VCC	17	Output of the internal regulator. Decouple this pin to the GND pin with a $1\muF$ ceramic capacitor.			



Preliminary Specification

### PACKAGE OUTLINE DIMENSIONS

**Type: QFN3\*3-20L** 



Symbol		nsions limeters	Dimensions In Inches		
·	MIN	MAX	MIN	MAX	
A	0.700	0.800	0.028	0.031	
A1	0.000	0.050	0.000	0.002	
A2	0.203 REF		0.008 REF		
D	2.924	3.076	0.115	0.121	
D1	1.400	1.600	0.055	0.063	
Е	2.924	3.076	0.115	0.121	
E1	1.400	1.600	0.055	0.063	
k	0.200 MIN		0.008 MIN		
b	0.150	0.250	0.006	0.010	
e	0.400 TYP		0.016 TYP		
L	0.324	0.476	0.013	0.019	



#### Preliminary Specification

# **Ordering Information**

Part Number	Voltage Range	Features	Operating Temperature	Package Type	Top Mark	SPQ
FH47120N20	2.8V ~ 16.0V	<ul> <li>Synchronous Boost(Step-up)</li> <li>97% Efficiency</li> <li>VFB Voltage: 1.0V</li> <li>IQ: 200uA</li> <li>Switching Frequency: 300kHz ~ 2.0MHz</li> <li>Current Limit: 10.0A</li> </ul>	-40°C to 85°C	QFN3.0*3.0-20L	BMF <u>xyz</u>	5000PCS/Reel

#### Note:

- FH47120 devices are Pb-free and RoHs compliant.
- The surface prints of our semiconductor devices are subject to change during the production process and do not involve changes in electrical parameters, and we will not separately state the notice.
- If you have any other custom purchase needs, please contact our sales department.
- > ForDevices reserves the right to amend and legally interpret the electrical parameters of this chip device.







#### **ESD SENSITIVITY CAUTION**

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.













#### Note:

- The information described herein is subject to change without notice.
- > ForDevices Inc. is not responsible for any problems caused by circuits or diagrams described herein whose related industrial properties, patents, or other rights belong to third parties. The application circuit examples explain typical applications of the products, and do not guarantee the success of any specific mass-production design.
- > Use of the information described herein for other purposes and/or reproduction or copying without the express permission of ForDevices Inc. is strictly prohibited.
- > The products described herein cannot be used as part of any device or equipment affecting the human body, such as exercise equipment, medical equipment, security systems, gas equipment, or any apparatus installed in airplanes and other vehicles, without prior written permission of ForDevices Inc.
- Although ForDevices Inc. exerts the greatest possible effort to ensure high quality and reliability, the failure or malfunction of semiconductor products may occur. The user of these products should therefore give thorough consideration to safety design, including redundancy, fire-prevention measures, and malfunction prevention, to prevent any accidents, fires, or community damage that may ensue.

▲ Update by Nov.2020